

AUTOMATED WAFER LAPPING SYSTEMAbstract of the Disclosure

An automated wafer lapping system including a robot which loads wafers from a cassette into a wafer carrier on a lapping machine one at a time and one after another. The robot is capable of delivering lapped wafers to a thickness gauging device for measuring the wafer thickness and recalibrating the lapping machine between each run. Openings in the wafer carriers for receiving wafers are sized closely to the wafer for minimal relative motion between the wafer and carrier. A centering jig and search program for the robot facilitate fast location of the wafers in the openings. The lapping system also inspects wafers for defects and sorts them accordingly after lapping.

Fig. 1